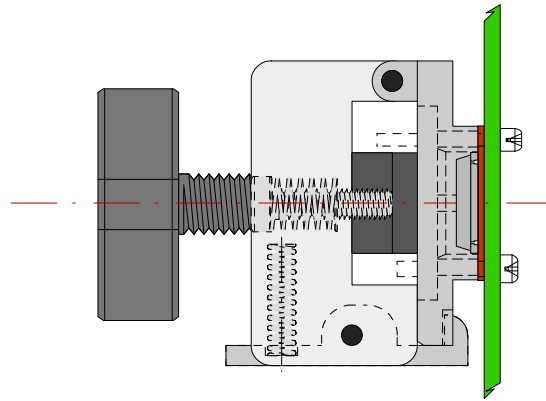
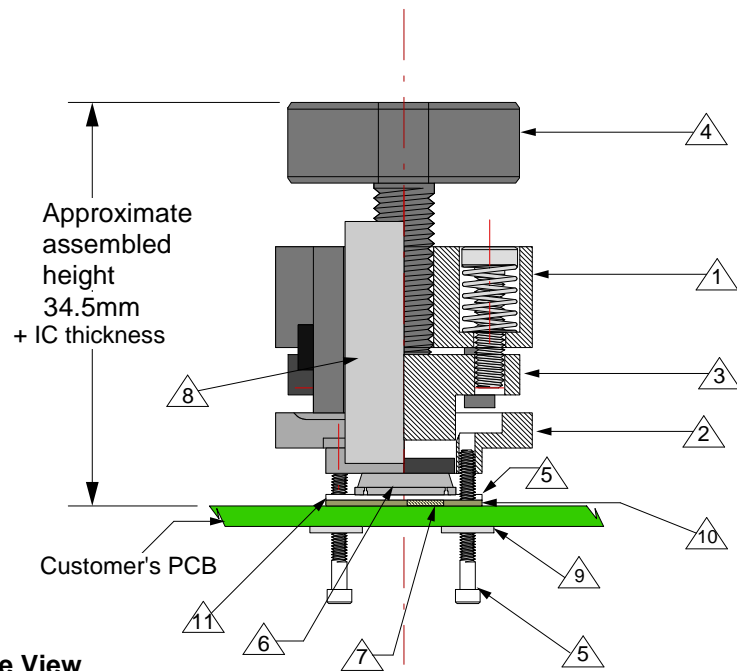


Top View



End View




Side View
(Section AA)

Features

- Directly mounts to target PCB (needs tooling holes) with hardware
- Minimum real estate required
- Compression plate distributes forces evenly
- Clamshell lid

Materials:

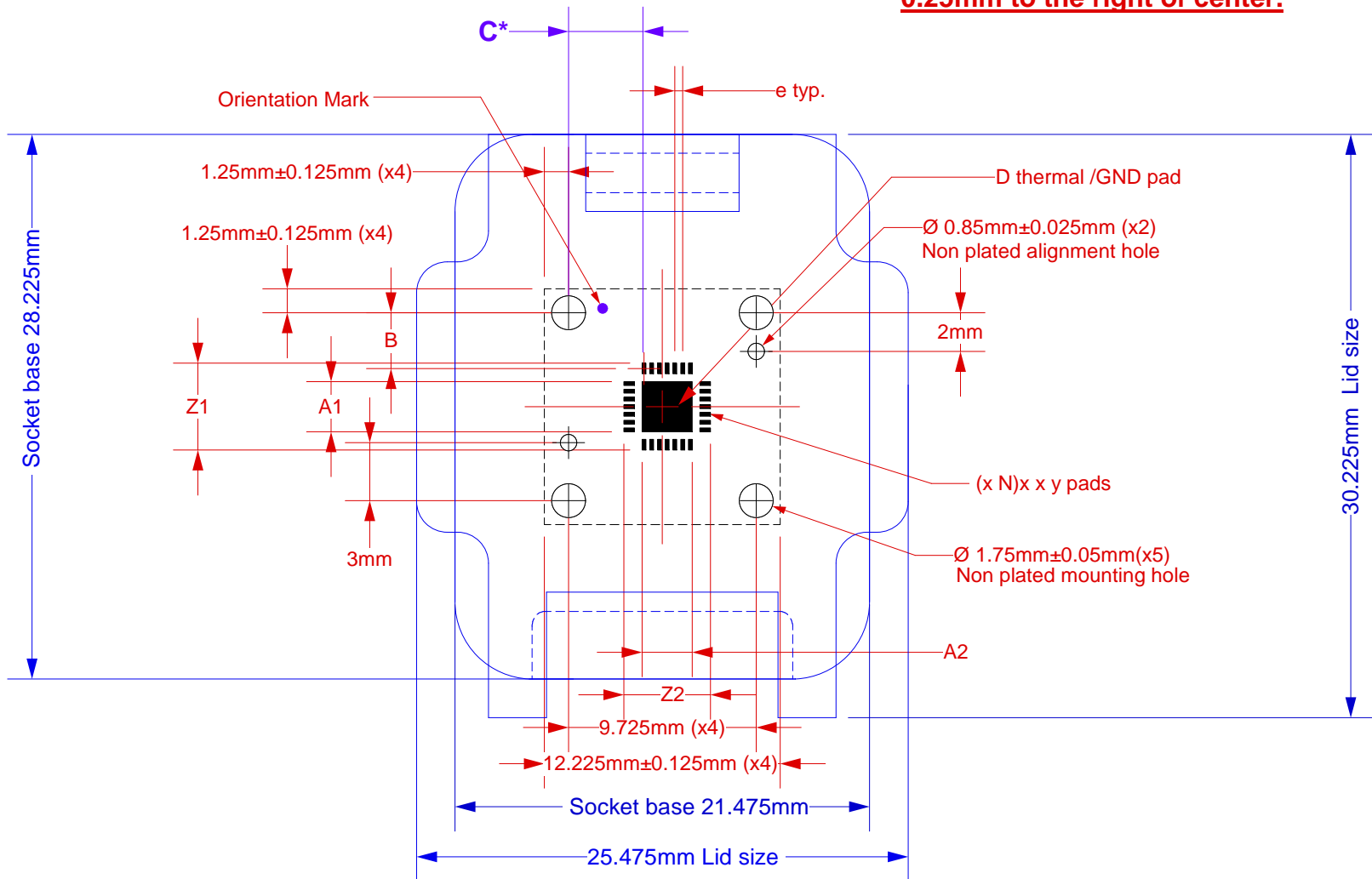
- 1 Clam Shell Lid: Black anodized Aluminum. Height = 16.5 mm.
- 2 Socket Base: Black anodized Aluminum. Height = 6 mm.
- 3 Compression Plate: Black anodized Aluminum. Thickness = 8.5 mm.
- 4 Compression Screw: Clear anodized Aluminum. Height = 25 mm, Fluted Knob
- 5 Socket Base Screw: Socket Head Cap Screw, alloy steel with black oxide finish, 0-80 Thread, 3/8" long.
- 6 Customer's QFN IC
- 7 Elastomer: 20 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.5mm.
- 8 Latch: Black anodized Aluminum.
- 9 Nylon washer: 1.73mm ID; 4.78mm OD 0.64mm thickness.
- 10 Elastomer Guide: Non-clad FR4. Thickness = 0.475mm.
- 11 IC Guide: Torlon Thickness = 0.45mm.

	CG-QFN-7005 Drawing	Status: Released	Scale: -	Rev: B
	© 2011 IRONWOOD ELECTRONICS, INC. Tele: (800) 404-0204 www.ironwoodelectronics.com	Drawing: E Smolentseva		Date: 2/24/11
		File: CG-QFN-7005 Dwg.mcd	Modified: 05/28/14, DH	

All tolerances: ±0.125mm (unless stated otherwise). Materials and specifications are subject to change without notice.

**Recommended PCB
Layout Top View**

***Note: QFN pattern is not symmetrical with respect to the mounting holes. It is offset 0.25mm to the right of center.**




Target PCB Recommendations

Total thickness: 1.6mm min.
Plating: Gold or Solder finish
PCB Pad height: Same or higher than solder mask

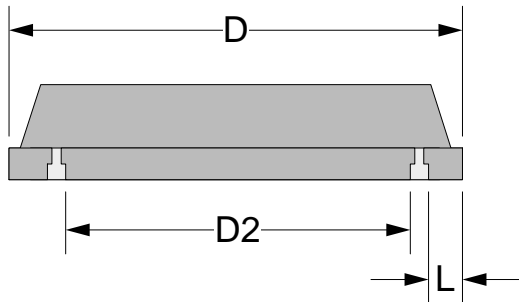
Recommended PCB Layout Tolerances: ±0.025mm unless stated otherwise.

All dimensions are in mm.

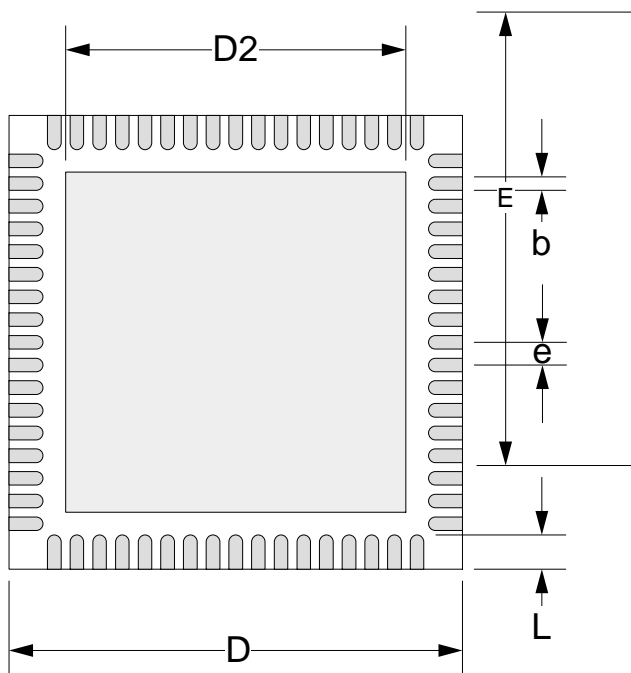
NOTE: Steel backing plate may be required based on end user's application


	CG-QFN-7005 Drawing	Status: Released	Scale: -	Rev: B
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		File: CG-QFN-7005 Dwg.mcd	Modified: 05/28/14, DH	

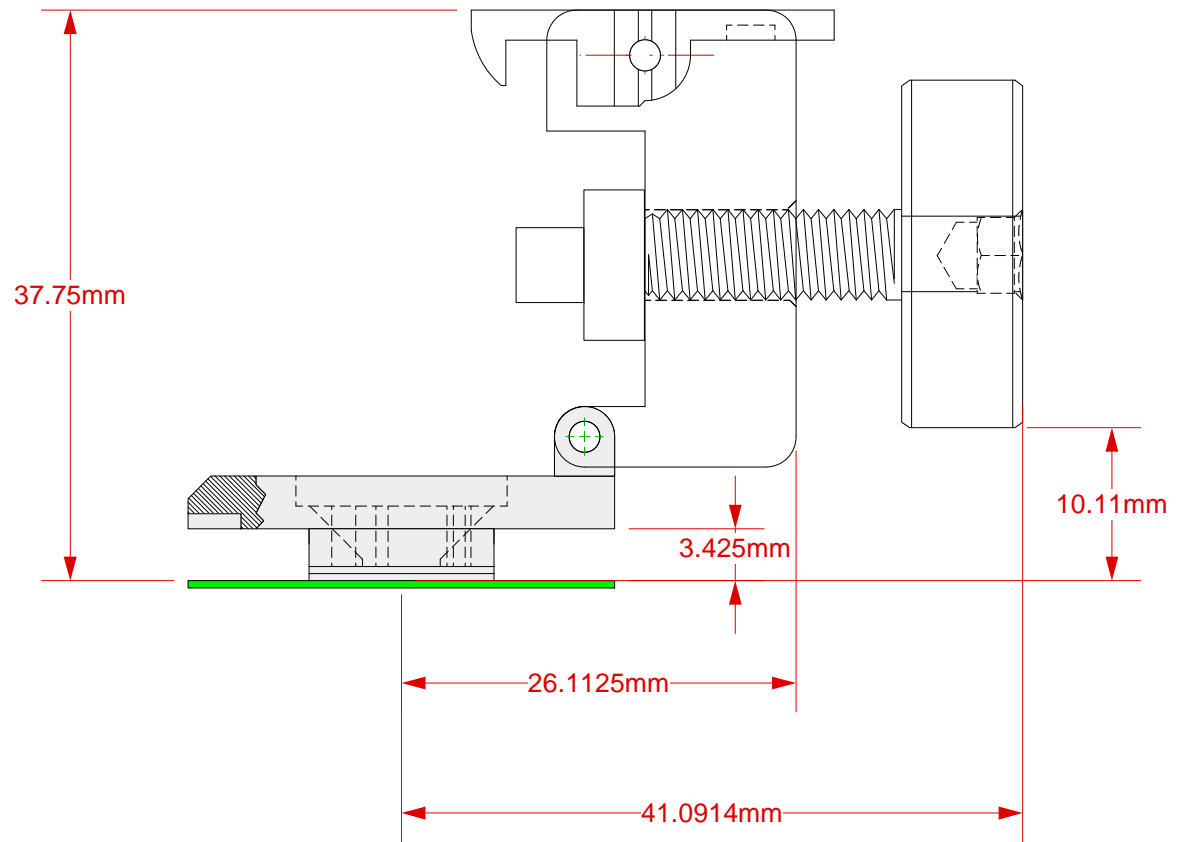
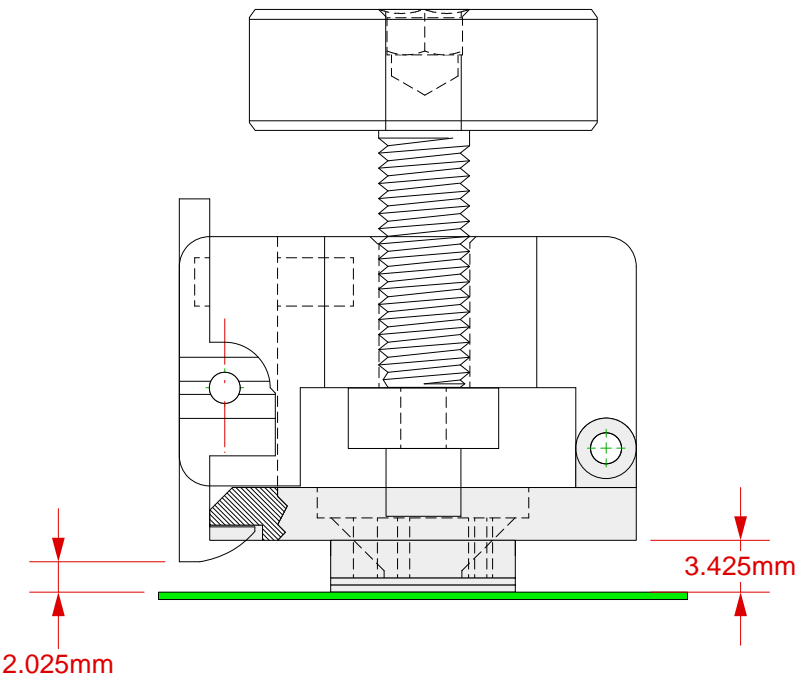
Package Code	C	B	Z1max	A1max	Z2max	A2 max	e	Xmax	Yref	N	Thermal Pad Recommendations
QFN24C	3.863	3.028	4.36	2.78	4.36	2.78	0.5	0.28	0.69	24	2.58.x 2.58
QFN28D	3.913	2.888	4.5	2.6	4.5	2.6	0.4	0.2	0.55	28	2.6.x 2.6




Package Code	e	D min	D max	E min	E max	b min	b max	L min	L max	D2	N
QFN24C	0.5	3.85	4.15	3.85	4.15	0.18	0.3	0.3	0.5	2.5	24
QFN28D	0.4	3.95	4.05	3.95	4.05	0.18	0.28	0.38	0.48	2.6	28



	CG-QFN-7005 Drawing		Status: Released	Scale: -	Rev: B
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			File: CG-QFN-7005 Dwg.mcd		Modified: 05/28/14, DH



Description: Keep out area information

	CG-QFN-7005 Drawing	Status: Released	Scale: -	Rev: B
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		File: CG-QFN-7005 Dwg.mcd	Modified: 05/28/14, DH	